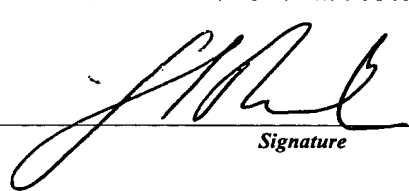
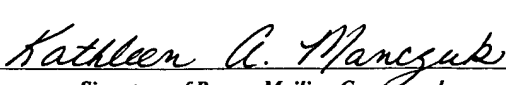


THW AF

AMENDMENT TRANSMITTAL LETTER (Large Entity)				Docket No. 90065.001020)XDEV1100)	
Applicant(s): Martin E. Kordes, et al.				JAN 11 2005	
Application No. 09/682,151	Filing Date July 27, 2001	Examiner Bradley W. Baumbach	Customer No. 34799	Group Art Unit 2815	Confirmation No. 5628
Invention: CONTACT METHOD FOR THIN SILICON CARBIDE EPITAXIAL LAYER AND SEMICONDUCTOR DEVICES FORMED BY THOSE METHODS					
<u>COMMISSIONER FOR PATENTS:</u>					
Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	16 -	20 =	0	x \$50.00	\$0.00
INDEP. CLAIMS	3 -	3 =	0	x \$200.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00
<input checked="" type="checkbox"/> No additional fee is required for amendment. <input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of _____ <input type="checkbox"/> A check in the amount of _____ to cover the filing fee is enclosed. <input type="checkbox"/> The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account <input type="checkbox"/> Any additional filing fees required under 37 C.F.R. 1.16. <input type="checkbox"/> Any patent application processing fees under 37 CFR 1.17. <input type="checkbox"/> Payment by credit card. Form PTO-2038. WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.					
 Signature			Dated: 7-JAN-2005		
Laurence S. Roach, Esq. Reg. No. 45, 044 Law Office of Thomas R. FitzGerald 16 E. Main St. Suite 210 Rochester, NY 14614-1808 Telephone (585) 454-2250 Fax (585) 454-6364			<div>I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on January 7, 2005 (Date)  Signature of Person Mailing Correspondence Kathleen A. Manczuk Typed or Printed Name of Person Mailing Correspondence</div>		
cc:					

CERTIFICATE OF MAILING BY FIRST CLASS MAIL (37 CFR 1.8)			Docket No.	
Applicant(s): Martin E. Kordes, et al			90065.001020(XDEV1100)	
Application No.	Filing Date	Examiner	Customer No.	Group Art Unit
09/682,151	July 27, 2001	Bradley W. Baumeister	34799	2815
Invention: CONTACT METHOD FOR THIN SILICON CARBIDE EPITAXIAL LAYER AND SEMICONDUCTOR DEVICES FORMED BY THOSE METHODS				
<p>I hereby certify that this <u>Response Under 37 CFR 1.116 (16 pages)</u></p> <p>(Identify type of correspondence)</p> <p>is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on</p> <p><u>January 7, 2005</u></p> <p>(Date)</p> <p><u>Kathleen A. Manczuk</u></p> <p>(Typed or Printed Name of Person Mailing Correspondence)</p> <p><u>Kathleen A. Manczuk</u></p> <p>(Signature of Person Mailing Correspondence)</p> <p>Note: Each paper must have its own certificate of mailing.</p>				



PATENT
Docket: 90065.001020 (XDEV1100)
Reply to Final Office Action of 30 Nov 2004

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

REPLY UNDER 37 CFR 1.116 - EXPEDITED PROCEDURE - EXAMINING GROUP 2815

Applicant	:	Martin E. Kordesch, et al.)	
)	
Serial No.	:	09/682,151)	
)	
Filed	:	27 July 2001)	Examiner: Baumeister
)	
For	:	CONTACT METHOD FOR THIN)	Art Unit: 2815
		SILICON CARBIDE EPITAXIAL)	
		LAYER AND SEMICONDUCTOR)	
		DEVICES FORMED BY THOSE)	
		METHODS)	

RESPONSE UNDER 37 CFR 1.116

Commissioner for Patents
MS: AF
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Final Office Action mailed 30 November 2004

Applicants submit the following Response.